



Revision: 1.0
Date: 4-Mar-05

Statement of Materials, Construction

LEAD-FREE -- 14L-PDIP -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.28468	Cu	7440-50-8	0.27700	27.61733	97.3
				Fe	7439-89-6	0.00669	0.66702	2.35
				Zn	7440-66-6	0.00034	0.03406	0.12
				P	7723-14-0	0.00009	0.00852	0.03
				Ag	7440-22-4	0.00057	0.05677	0.2
2	Die	Silicon Chip	0.00550	Si	7440-21-3	0.00547	0.54562	99.5
3	Die attach material	Conductive Epoxy	0.00134	Epoxy resin (5-25)	Proprietary	0.00020	0.02000	15
				Silver (70-85)	7440-21-3	0.00106	0.10601	79.5
				Aromatic Amine (1-10)	Proprietary	0.00007	0.00733	5.5
4	Wire	Gold	0.00059	Au	7440-57-5	0.00059	0.05882	99.99
5	Lead Finish	Tin	0.0088328	Sn	7440-31-5	0.00883	0.88065	100
6	Encapsulation	Epoxy Resin	0.70204	Fused Silica	7631-86-9	0.47177	47.03672	67.2
				Epoxy resin	29690-82-2	0.14041	13.99902	20
				Phenol Resin	9003-35-4	0.05265	5.24963	7.5
				Antimony trioxide	1309-64-4	0.02106	2.09985	3
				Brominated Epoxy Resin	40039-93-8	0.01404	1.39990	2
				Carbon Black	1333-86-4	0.00211	0.20999	0.3
Total Package weight			1.00298					

Note: Composition derived from MSDS and material C of C from Vendors;
Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead*	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%